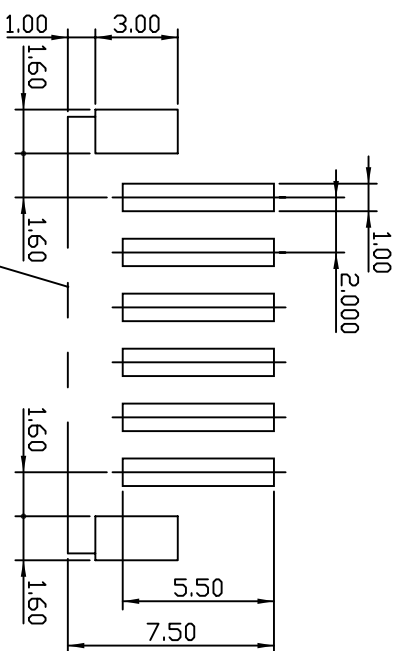
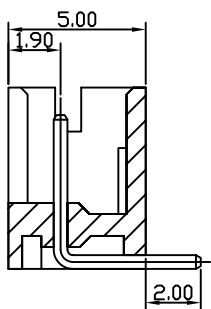
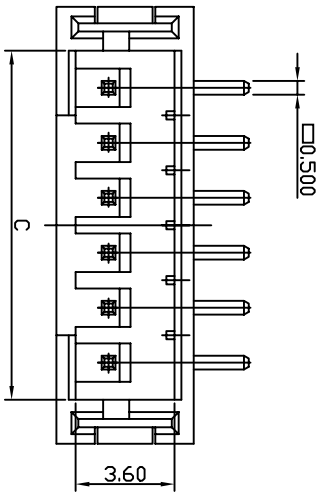


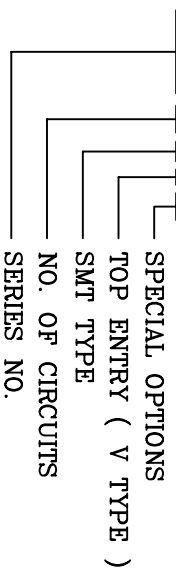
REV.	ECO. NO.	CHG.	APPD.
A	DWG REL.		



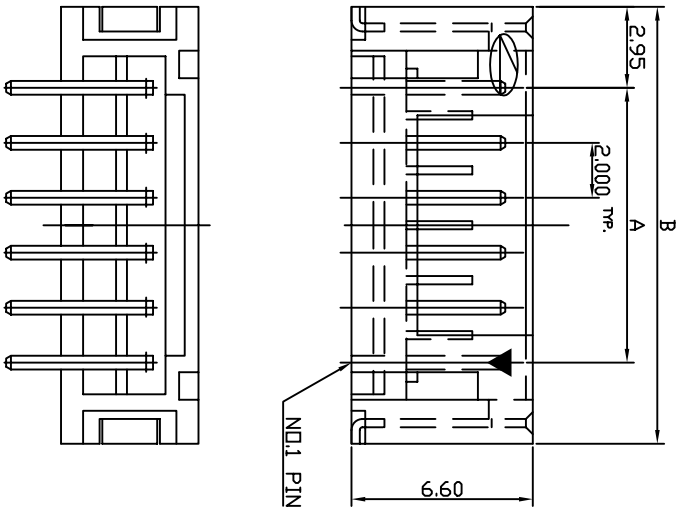
END FACE OF WAFER  
ON THE MATING FACE  
RECOMMENDED PCB LAYOUT

ORDERING INFORMATION:

2011P\*\*MV00



1. DIMENSIONS SHOWN: mm
2. MOLDING MATERIAL: QUESTRA EA535 UL94V-0 (SPS+30%GF)
3. CONTACT BASE MATERIAL: BRASS
4. SOLDER TAB BASE MATERIAL: BRASS, TIN PLATED
5. CONTACT PLATING: TIN PLATED
6. THE COPLANARITY OF PINS'SOLDERING SURFACE LESS THAN 0.15.



Part No.	DIM. A	DIM. B	DIM. C	Part No.	DIM. A	DIM. B	DIM. C
2011P02MV00	2,000	7.9	4.70	2011P09MV00	16,000	21.9	18.70
2011P03MV00	4,000	9.9	6.70	2011P10MV00	18,000	23.9	20.70
2011P04MV00	6,000	11.9	8.70	2011P11MV00	20,000	25.9	22.70
2011P05MV00	8,000	13.9	10.70	2011P12MV00	22,000	27.9	24.70
2011P06MV00	10,000	15.9	12.70	2011P13MV00	24,000	29.9	26.70
2011P07MV00	12,000	17.9	14.70				
2011P08MV00	14,000	19.9	16.70				

莱科(苏州)精工材料有限公司 LECO CORPORATION		APPROVED BY:	PART NO.:
GENERAL TOLERANCE		CHECKED BY:	TITLE:
X. ±	X. ± 2'		SMD WAFER
.X ± 0.30	.X' ±	DRAW BY:	DRAWING NO.:
.XX ± .012	.XX' ±		201123S
.XX ± 0.20	.XX' ±	UNITS	SCALE
.XXX ± .008	.XXX' ±	mm	5/1 A4
.XXX ± .004	.XXX' ±		SIZE
			1/1
			REV.
			A